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RELATED PATENT DATA

This patent application is a divisional resulting from U.S. Patent Application Serial No. 09/388,826, filed September 1, 1999, entitled "Low k Interlevel Dielectric Layer Fabrication Methods", naming Weimin Li, Zhiping Yin, and William Budge as inventors, and which is now U.S. Patent No. [REDACTED], the disclosure of which is incorporated by reference.--

Amended Claims

Please cancel claims 1-25 and 34-51.

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